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FOR IMMEDIATE RELEASE

CONTACT:

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Greetings to our Valued SMTA Speakers and Industry Colleagues



In conjunction with



Call for Papers 2010 for the Technology Conference

The SMTA China cordially invites you to participate in **SMTA China South Conference** located in **Shenzhen for 2010**. This event, held in conjunction with NEPCON South China 2010, will address the industry's most pressing issues in electronics manufacturing, advanced packaging and lead-free reliability.

Topical coverage includes:

Environment Friendly Operation

Lead-free alloys in combination with surface finishes. How do new alloys perform on different surface finishes?

Tin whiskers, board cleaning, environmental issues.

Solar and/or other alternative energy topics.

Solar SMT

Alternative solder materials.

Cleaning technology

Lead-free reliability studies.

Operation Excellence

Bare board process assessment or benchmarking-how to define process capability limits of PWB supplies beyond IPC-1710 audit form.

Best profile for reflow.

Solder paste printing, how to develop paste printing SPC process

PCB surface delamination by excess heat.

Inspection of solder connections between connector and PWB-residual flux, in particular

Reliability testing for Pb-free solders-what tests to do and at what levels?



Printed electronics-circuit boards and passives
PCB/laminate issues. Failure analysis.
Effective PCBA reworking
Intrusive solder on lead-free

Emerging Technology Focus
PoP rework/repair. PoP process control
01005 placement
Practical PoP assembly issues, rework of LGAs
Flexible electronics-assembly/packaging, etc.
Advanced next generation packages/process topics (i.e. flexible substrate bumping).
Alternative soldering mechanism, induction soldering, laser soldering, solderless connections, etc.
Alternative PCB finish, etc.

SMTA China solicits technical papers for presentation in the **Technology Conference**. Inclusion in the Technology Conference requires strictly technical papers (**complimentary presentation slot for speakers**) subject to final acceptance by the Technical Advisory Committee of SMTA China. All papers including abstract and biography for inclusion in the Conference Proceedings requested in both **Chinese and English**. **All papers (powerpoint) must be in Chinese and shall be presented in Chinese.**



If you or your company wishes to share pertinent information with the highly qualified audience of **SMTA China** please submit your abstract to Michael Wong by email to peggy@smta.org. Please include your name, job title, company affiliation, and all pertinent contact information **as well as your choice of Technology Conference for your paper.**

Deadlines for Abstract and Speaker Bio submission:

SMTA China South Conference 20 May 2010

In order to appreciate the speakers of excellent information sharing, SMTA China would like to honor the best paper, and the speaker of best presentation, which award will be presented during the Annual Breakfast Reception which will be held in the morning of 1 September in Shenzhen.

Thank you for your support of SMTA China and we look forward to hearing from you.

Contact and Enquiry: Ms. Peggy Chen, Executive Administrator of SMTA China,
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2010年4月26日

尊敬的表面装贴技术协会演讲者和业内同行



同期举行于:



为高科技技术研讨会 2010 征集论文

SMTA 中国诚意的邀请您参加 2010 年在深圳举办的 SMTA 华南高科技会议。此次会议将与第十六届华南国际电子生产设备暨微电子工业展联合举办，会议将涉及行业中最热门的话题，包括电子制造，先进的包装和无铅可靠性。

主题覆盖面包括:

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SMTA 中国为高科技技术研讨会中的演讲征集技术论文。高科技技术研讨会的技术论文主题及内容必须为纯技术论文，经由 **SMTA 中国**技术顾问委员会最终决定后，将被列入会议题目(高科技技术研讨会的演讲者无需缴付赞助费)。所有论文包括文章大纲和演讲者个人简介要求中文和英文刊登在技术论文集中。所有演讲（幻灯片形式的演讲稿）必须为中文并且以中文讲解。



如果您和您的公司希望与 **SMTA 中国**的会员及专业观众分享贵公司的有关信息，请发邮件提交您的文章大纲给 **SMTA 中国**技术顾问委员会主席王玉辉先生至 peggy@smta.org 并写上您的名字、工作头衔和公司的相关信息以及有关联系信息并且注明您的技术论文是投稿于高科技技术研讨会。

提交文章大纲和演讲者个人简介的截止日期:

SMTA 华南高科技技术研讨会 2010年5月20日

为了感谢演讲者们优秀信息的分享, **SMTA 中国**将于深圳9月1日早上的周年早餐会上颁发最佳论文奖和最佳演讲奖。

感谢您支持 **SMTA 中国**，期待您的消息。

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